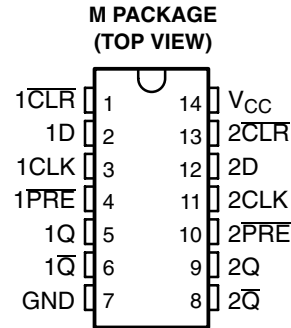


CD74ACT74-Q1

DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

SCHS349A – DECEMBER 2003 – REVISED JANUARY 2008

- Qualified for Automotive Applications
- Inputs Are TTL-Voltage Compatible
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ± 24 -mA Output Drive Current
 - Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design



description/ordering information

The CD74ACT74 dual positive-edge-triggered device is a D-type flip-flop.

A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

ORDERING INFORMATION†

T _A	PACKAGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SOIC – M Tape and reel	CD74ACT74QM96Q1	ACT74Q

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

FUNCTION TABLE (each flip-flop)

INPUTS				OUTPUTS	
PRE	CLR	CLK	D	Q	Q̄
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H [§]	H [§]
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q ₀	Q̄ ₀

§ This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



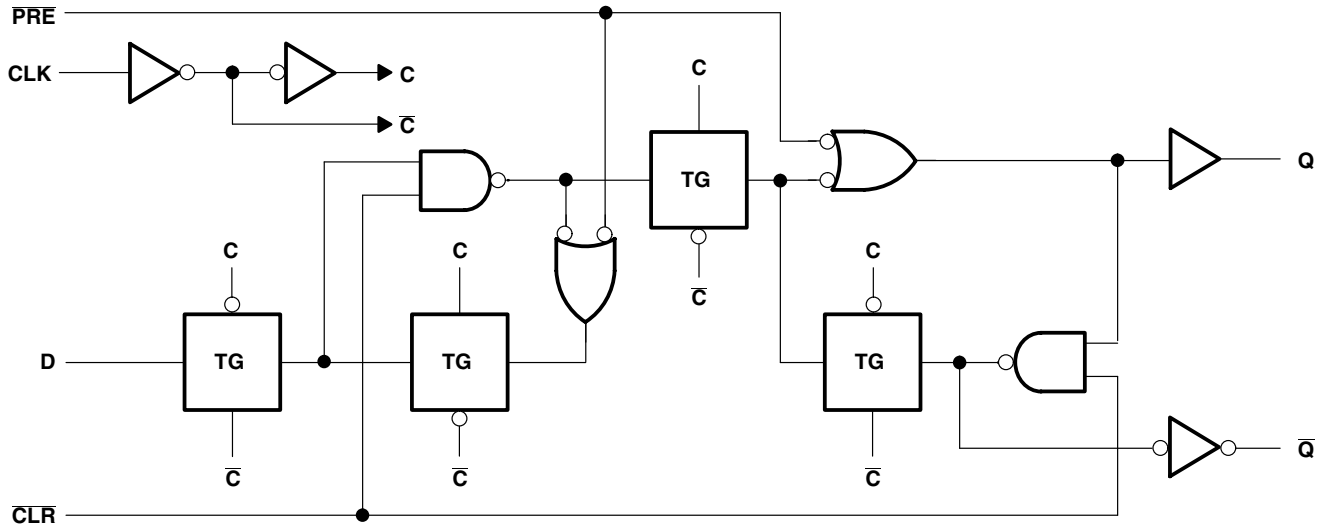
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logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 50 mA
Continuous current through V_{CC} or GND	± 100 mA
Package thermal impedance, θ_{JA} (see Note 2)	86°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

	$T_A = 25^\circ\text{C}$		-40°C to 125°C		UNIT
	MIN	MAX	MIN	MAX	
V_{CC} Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH} High-level input voltage	2		2		V
V_{IL} Low-level input voltage		0.8		0.8	V
V_I Input voltage	0	V_{CC}	0	V_{CC}	V
V_O Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH} High-level output current		-24		-24	mA
I_{OL} Low-level output current		24		24	mA
$\Delta t/\Delta v$ Input transition rise or fall rate		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C		-40°C to 125°C		UNIT
			MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -50 μA	4.5 V	4.4	4.4	V	
		I _{OH} = -24 mA	4.5 V	3.94	3.7		
		I _{OH} = -50 mA [†]	5.5 V		3.85		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 50 μA	4.5 V	0.1	0.1	V	
		I _{OL} = 24 mA	4.5 V	0.36	0.5		
		I _{OL} = 50 mA [†]	5.5 V		1.65		
I _I	V _I = V _{CC} or GND	5.5 V	±0.1	±1	μA		
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V	4	80	μA		
ΔI _{CC} [‡]	V _I = V _{CC} - 2.1 V	4.5 V to 5.5 V	2.4	3	mA		
C _i			10	10	pF		

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 75-Ω transmission-line drive capability at 125°C.

[‡] Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
Data	0.53
PRE or CLR	0.58
CLK	1

Unit load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		-40°C to 125°C		UNIT
		MIN	MAX	
f _{clock}	Clock frequency		85	MHz
t _w	Pulse duration	PRE or CLR low	5	ns
		CLK	5.7	
t _{su}	Setup time	Data	4	ns
t _h	Hold time	Data after CLK↑	0	ns
t _{rec}	Recovery time, before CLK↑	CLR↑ or PRE↑	2.7	ns

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-40°C to 125°C		UNIT
			MIN	MAX	
f_{max}			85		MHz
t_{PLH}	CLK	Q or \bar{Q}	2.4	9.5	ns
t_{PHL}			2.4	9.5	
t_{PLH}	PRE or \bar{CLR}	Q or \bar{Q}	2.9	11.5	ns
t_{PHL}			3.1	12.5	

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TYP	UNIT
C_{pd}	Power dissipation capacitance	55	pF

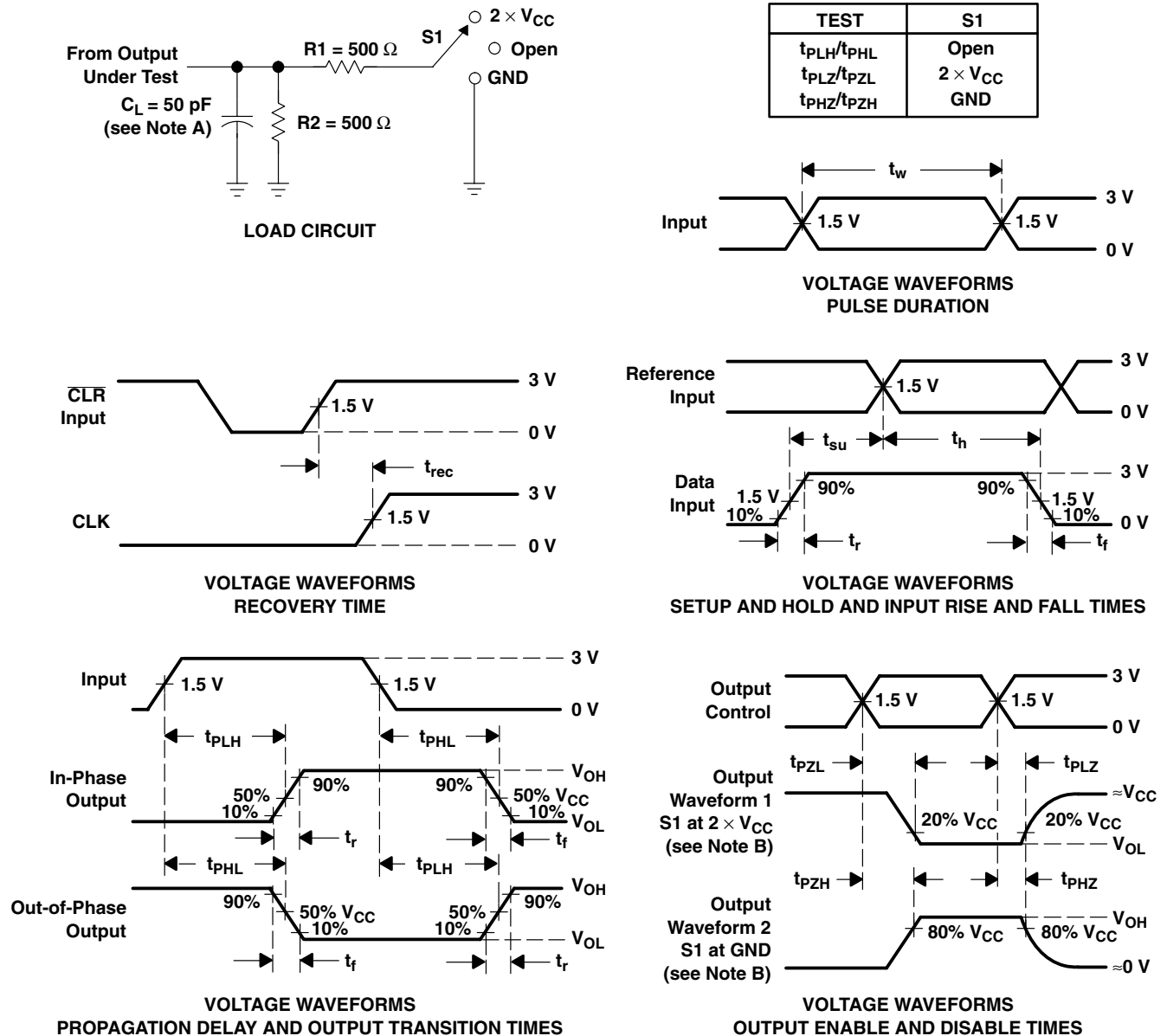


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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 3$ ns, $t_f = 3$ ns. Phase relationships between waveforms are arbitrary.
 - D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
 - E. The outputs are measured one at a time with one input transition per measurement.
 - F. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - G. t_{PZL} and t_{PZH} are the same as t_{en} .
 - H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
CD74ACT74QM96G4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74ACT74QM96Q1	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF CD74ACT74-Q1 :

● Catalog: [CD74ACT74](#)

● Military: [CD54ACT74](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

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